MC100ELT23

5 V Dual Differential PECL to TTL Translator

ON Semiconductor®

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Description

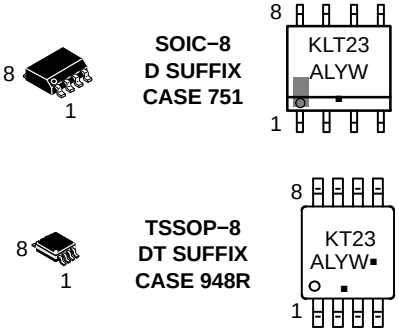
The MC100ELT23 is a dual differential PECL to TTL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the dual gate design of the ELT23 makes it ideal for applications which require the translation of a clock and a data signal.

The PECL inputs are differential; therefore, the MC100ELT23 can accept any standard differential PECL input referenced from a V_{CC} of 5.0 V.

Features

- 3.5 ns Typical Propagation Delay
- 24 mA TTL Outputs
- Flow Through Pinouts
- The 100 Series Contains Temperature Compensation
- Operating Range V_{CC} = 4.75 V to 5.25 V with GND = 0 V
- Internal Input 50 KΩ Pulldown Resistors
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAMS*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

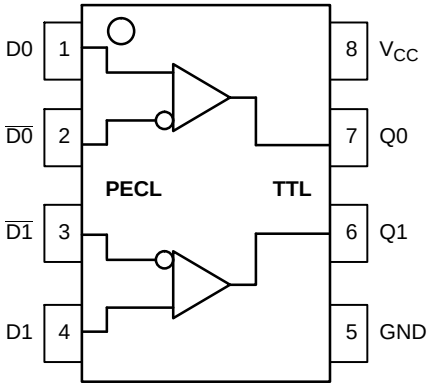


Figure 1. 8−Lead Pinout (Top View) **and Logic Diagram**

Table 1. PIN DESCRIPTION

Pin	Function
Qn	TTL Outputs
Dn, $\overline{Dn}$	PECL Differential Inputs
V_{CC}	Positive Supply
GND	Ground

Table 2. ATTRIBUTES

Characteristics		Value
Internal Input Pulldown Resistor		50 kΩ
Internal Input Pullup Resistor		N/A
ESD Protection	Human Body Model Machine Model	> 2 kV > 400 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb−Free Pkg
	SOIC−8 TSSOP−8	Level 1 Level 3
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in
Transistor Count		91 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Power Supply	GND = 0 V		7	V
V_I	Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	0 to 6	V
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	SOIC−8 SOIC−8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	SOIC−8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	TSSOP−8 TSSOP−8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	TSSOP−8	41 to 44 ± 5%	°C/W
T_{sol}	Wave Solder Pb−Free	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. PECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 2)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{IH}	Input HIGH Voltage (Single−Ended) (Note 3)	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3190		3525	3190		3525	3190		3525	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 4)	2.2		5.0	2.2		5.0	2.2		5.0	V
I_{IH}	Input HIGH Current			255			175			175	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

2. Input parameters vary 1:1 with V_{CC}. V_{CC} can vary ± 0.25 V.
3. TTL output R_L = 500 Ω to GND.
4. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}

Table 5. TTL OUTPUT DC CHARACTERISTICS V_{CC} = 4.75 V to 5.25 V; T_A = −40°C to 85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = −3.0 mA	2.4		(Note 5)	V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA			0.5	V
I_{CCH}	Power Supply Current			23	33	mA
I_{CCL}	Power Supply Current			26	36	mA
I_{OS}	Output Short Circuit Current		−150		−60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

5. Max level is V_{CC} − 0.7 V by design.

Table 6. AC CHARACTERISTICS V_{CC}= 5.0 V; GND= 0.0 V (Note 6 and Note 7)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency					100					MHz
t_{JITTER}	Random Clock Jitter (RMS)					35					ps
t_{PLH}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
t_{PHL}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
V_{PP}	Input Swing (Note 8)	200		1000	200		1000	200		1000	mV
t_r/t_f	Output Rise Time (10−90%) Output Fall Time (10−90%)					1.6 1.1					ns ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

6. V_{CC} can vary ± 0.25 V.
7. TTL output R_L = 500 Ω to GND, and C_L = 20 pF to GND. Refer to Figure 2.
8. V_{PP}(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈ 40.

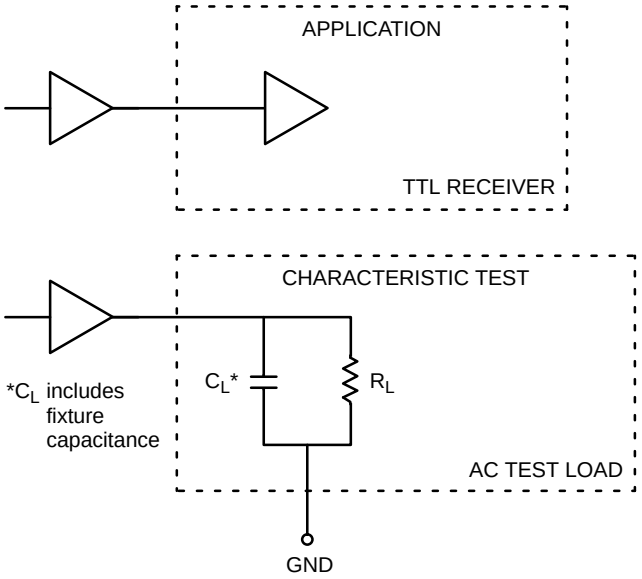


Figure 2. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping†
MC100ELT23DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC100ELT23DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC100ELT23DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC100ELT23DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D − ECL Clock Distribution Techniques

AN1406/D − Designing with PECL (ECL at +5.0 V)

AN1503/D − ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D − Metastability and the ECLinPS Family

AN1568/D − Interfacing Between LVDS and ECL

AN1672/D − The ECL Translator Guide

AND8001/D − Odd Number Counters Design

AND8002/D − Marking and Date Codes

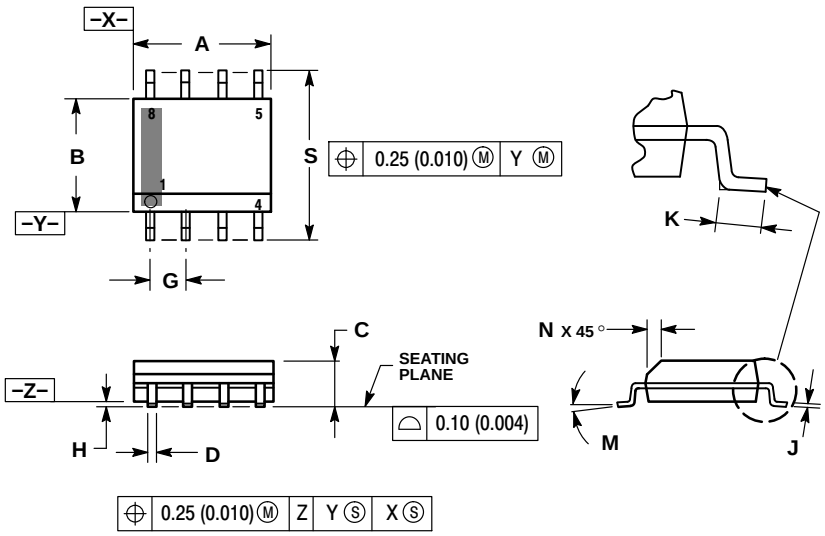
AND8020/D − Termination of ECL Logic Devices

AND8066/D − Interfacing with ECLinPS

AND8090/D − AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

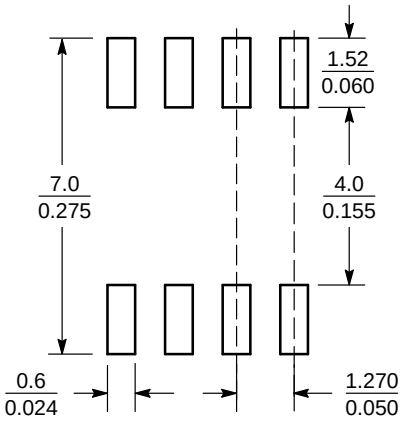
SOIC−8 NB
CASE 751−07
ISSUE AK



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

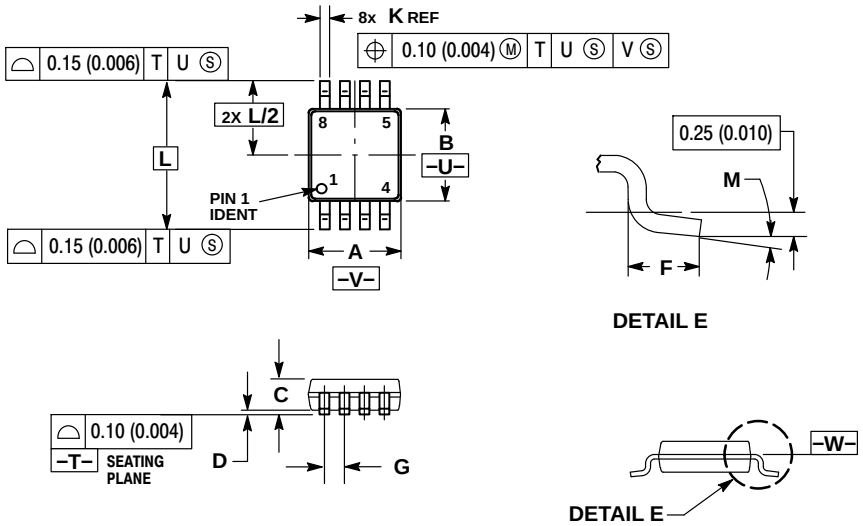


SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
DT SUFFIX
CASE 948R−02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0 °	6 °	0 °	6 °

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC).

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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